

**ON-CIRCUIT BOARD CONTINUITY TESTER****ABSTRACT**

For qualification testing in product development, a test assembly contains a surrogate circuit board (7) and surrogate electronic modules (5) supported thereon. The terminals (5a-5j) of the modules are joined to respective bonding pads (2a-2j) on the circuit board to form bonded joints. The modules terminals and the wiring of the associated bonding pads is configured to produce at least one test series circuit (21) associated with each module that includes the bonded joints. A tester (9) supported on the circuit board monitors the test series circuit and produces a persistent indication (10) should a break or interruption occur in a bonded joint or any other portion of the test series circuit. This allows indications of transient breaks that occurred when the test assembly was being subjected to stresses, such as those induced by temperature excursions, mechanical vibration, and/or mechanical shock to be preserved and recorded at a later time.